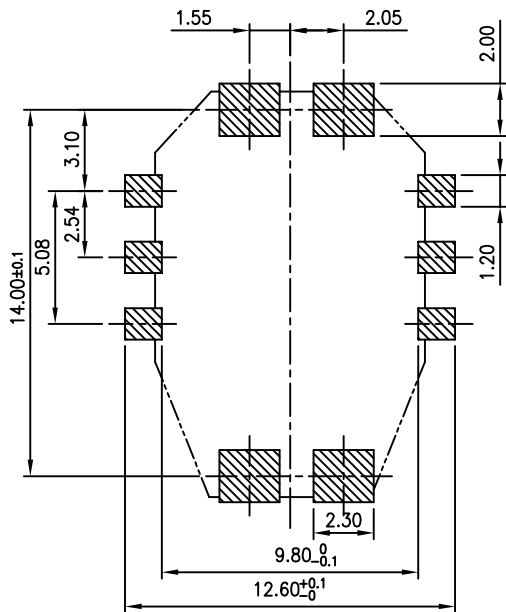
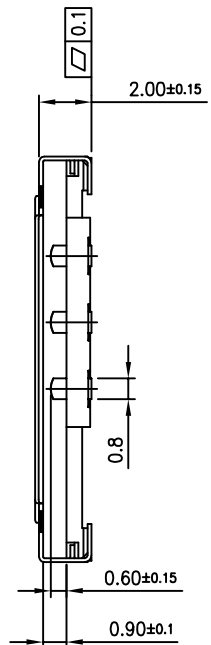
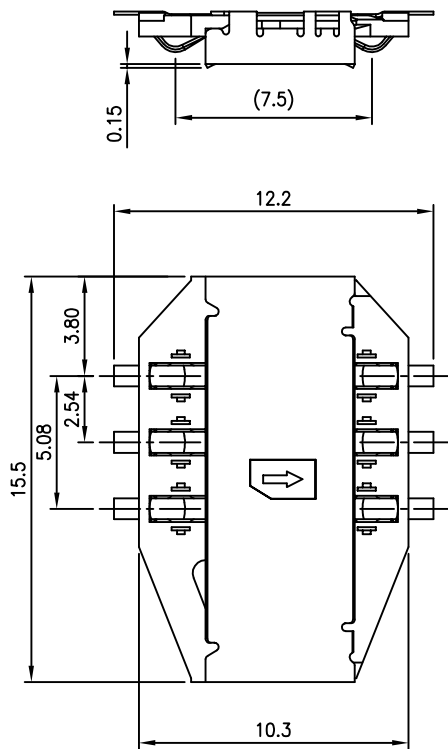


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR RELEASE	BONNIE	2008.10.14



SPECIFICATIONS:

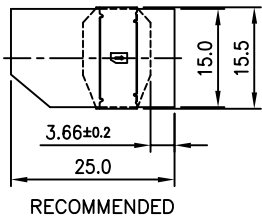
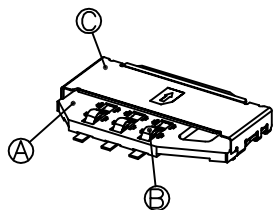
1. OTHER GENERAL SPEC. TO REFER "2SM1507 SERIES SPEC".
2. SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260°C 10 SECS
3. GREEN PRODUCT IDENTIFICATION MARK ON JACK:
4. GREEN PRODUCT IDENTIFICATION LABEL ON PACKAGING: **G.P. PASS**
5. FOR REFLOW SOLDERING LEAD-FREE PROCESS.
6. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
7. PACKAGE : SEE "2SM1507 SERIES" PACKAGE

PART NO.

2SM1507-000111

- PACKAGE
- 1: TAPE & REEL
- HOUSING COLOR
- 1: BLACK
- CONTACT PLATING
- 1: GOLD FLASH

Recommend PCB Layout  
Tolerance: ±0.05mm (Top view)



C	SHELL	1	SUS304	Au PLATING
B	CONTACT	6	COPPER ALLOY	GOLD FLASH
A	HOUSING	1	PA9T UL 94V-0	BLACK COLOR
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES			Singatron Enterprise Co., Ltd. 信音企業股份有限公司	
DECIMALS:	ANGLES:	TITLE	SIM CARD 2.0H	
X : ±0.5	X : ±2°	DWN	BONNIE2008.10.14 PART NO. 2SM1507-000111	
X.X : ±0.3	X.X : ±1°	CHKD	JOHNSON2008.10.14	SCALE 1:1 UNIT: mm
X.XX : ±0.2		APVD	JOHNSON2008.10.14	SIZE: A3 SHEET: 1 OF 1 REV: A
<b>CUSTOMER COPY</b>				